



15N10

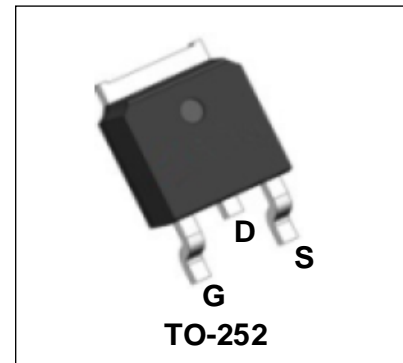
100V N-Channel Enhancement Mode Power MOSFET

Description

15N10 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

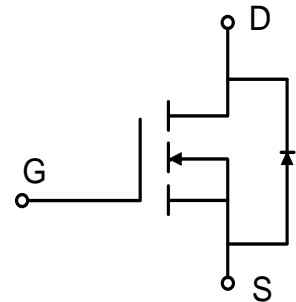
Features

- $V_{DS} = 100V$, $I_D = 14.6A$
 $R_{DS(on)} < 90m\Omega$ @ $V_{GS} = 10V$
 $R_{DS(on)} < 105m\Omega$ @ $V_{GS} = 4.5V$
- Green Device Available
- Low Gate Charge
- Advanced High Cell Density Trench Technology
- 100% EAS Guaranteed



Applications

- Power Management Switches
- DC/DC Converters



Absolute Maximum Ratings ($T_A = 25^\circ C$, unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V_{DS}	100	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Continuous Drain Current	I_D	$T_C = 25^\circ C$	14.6	A
		$T_C = 100^\circ C$	10	
Pulsed Drain Current ¹	I_{DM}	58	A	
Single Pulse Avalanche Energy ²	EAS	3.2	mJ	
Total Power Dissipation	P_D	41.7	W	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$	

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	50	$^\circ C/W$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	3	$^\circ C/W$

Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	100	-	-	V
Gate-body Leakage current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T _J =25°C	V _{DS} =100V, V _{GS} = 0V	-	-	1	μA
	T _J =100°C		-	-	100	
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.2	-	2.5	V
Drain-Source on-Resistance ⁴	R _{DS(on)}	V _{GS} = 10V, I _D = 5A	-	65	90	mΩ
		V _{GS} = 4.5V, I _D = 3A	-	75	105	
Forward Transconductance ⁴	g _{fs}	V _{DS} =5V, I _D =5A	-	12	-	S
Dynamic Characteristics⁵						
Input Capacitance	C _{iss}	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz	-	1220	-	pF
Output Capacitance	C _{oss}		-	53	-	
Reverse Transfer Capacitance	C _{rss}		-	42	-	
Gate Resistance	R _g	f = 1MHz	-	1.3	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q _g	V _{GS} = 10V, V _{DS} = 50V, I _D =5A	-	20.6	-	nC
Gate-Source Charge	Q _{gs}		-	4	-	
Gate-Drain Charge	Q _{gd}		-	3.7	-	
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10V, V _{DD} = 50V, R _G = 3Ω, I _D = 5A	-	4.7	-	ns
Rise Time	t _r		-	21	-	
Turn-Off Delay Time	t _{d(off)}		-	20	-	
Fall Time	t _f		-	16	-	
Body Diode Reverse Recovery Time	t _{rr}	I _F =5A, dI/dt=100A/μs	-	35	-	ns
Body Diode Reverse Recovery Charge	Q _{rr}		-	45.5	-	nC
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	I _S = 1A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	T _C =25°C	I _S	-	-	14.6	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The EAS data shows Max. rating . The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=8A.
3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

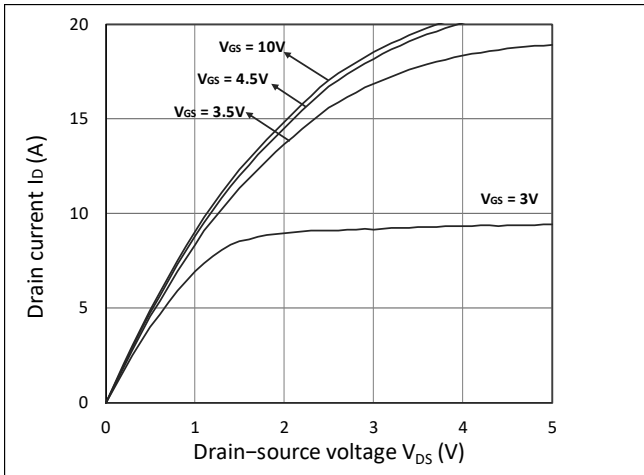


Figure 1. Output Characteristics

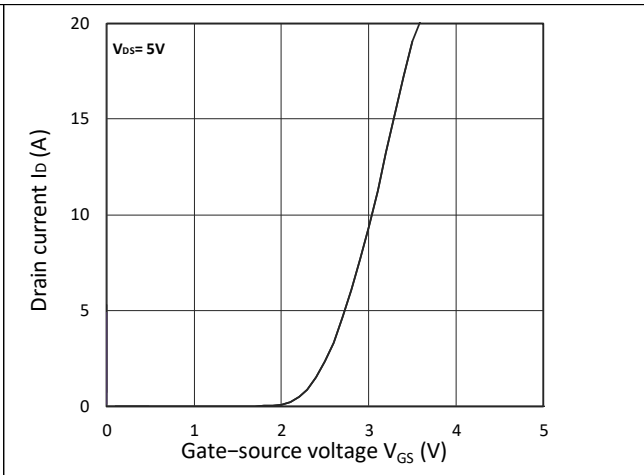


Figure 2. Transfer Characteristics

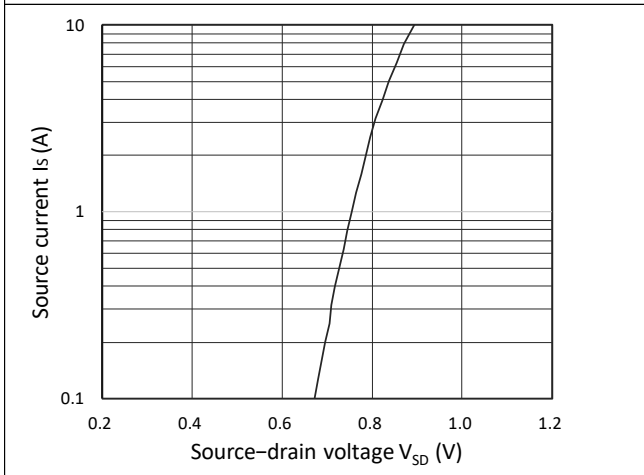


Figure 3. Forward Characteristics of Reverse

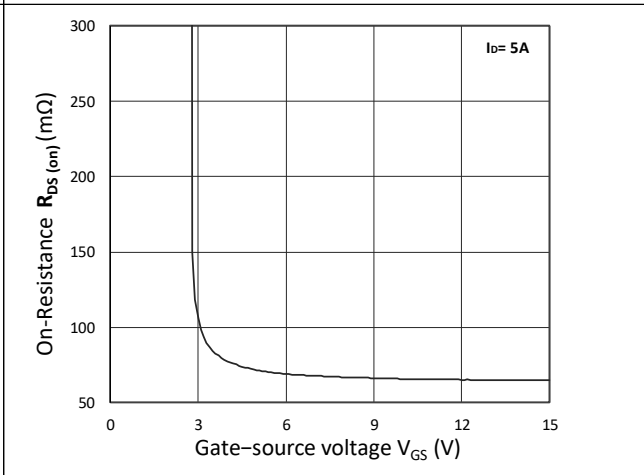


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

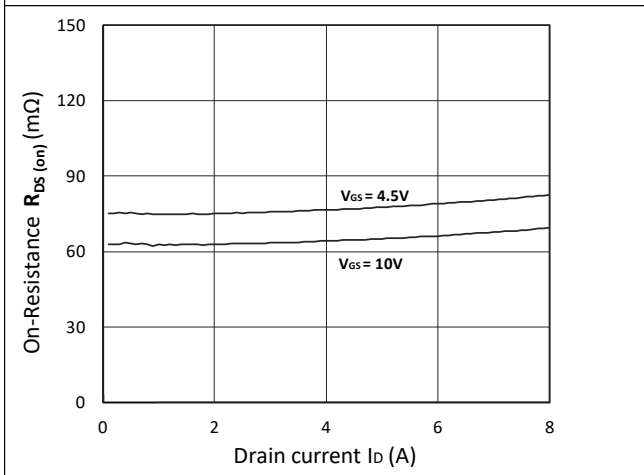


Figure 5. $R_{DS(ON)}$ vs. I_D

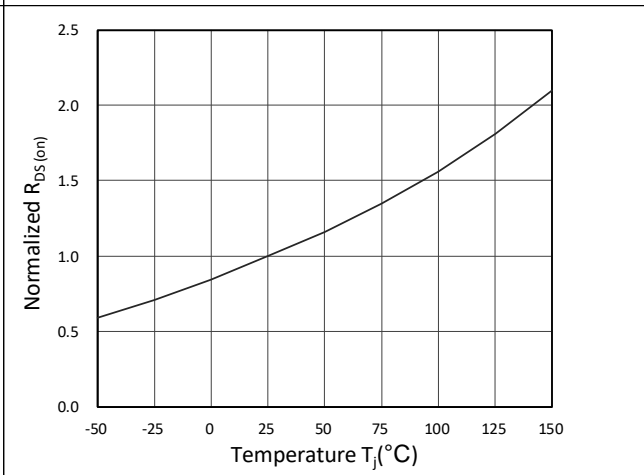


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

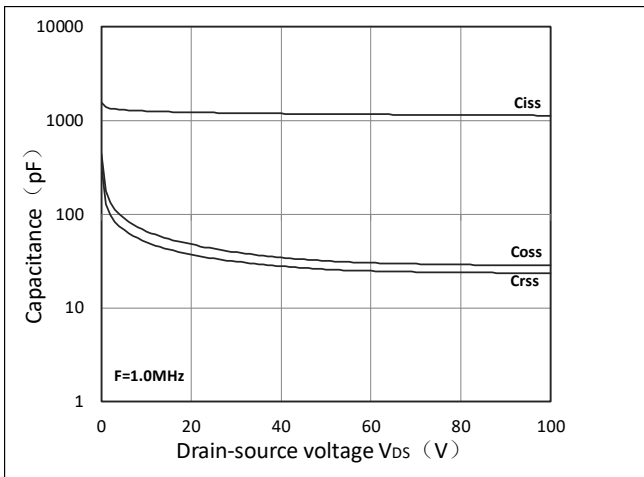


Figure 7. Capacitance Characteristics

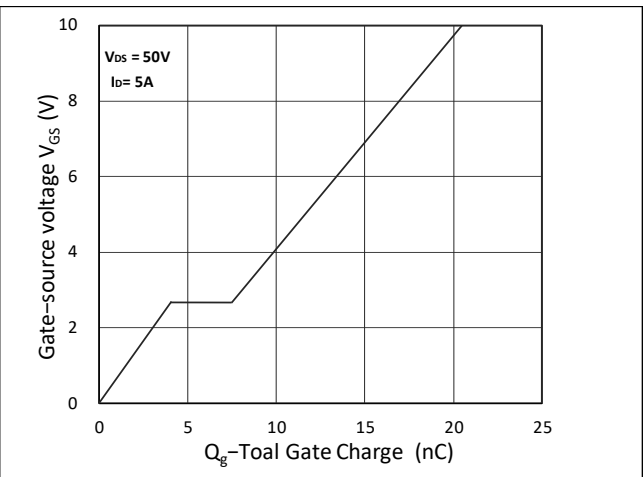


Figure 8. Gate Charge Characteristics

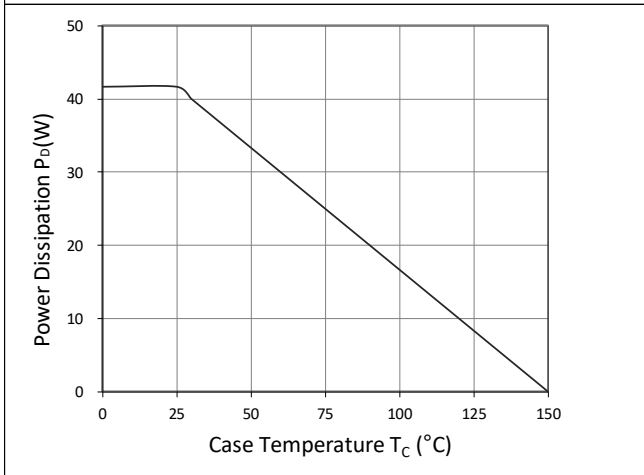


Figure 9. Power Dissipation

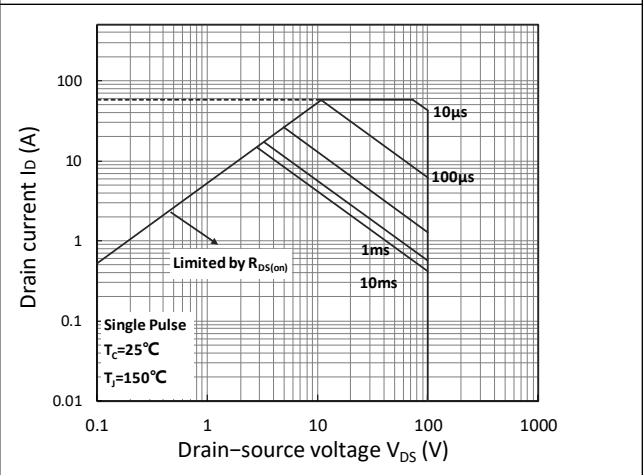


Figure 10. Safe Operating Area

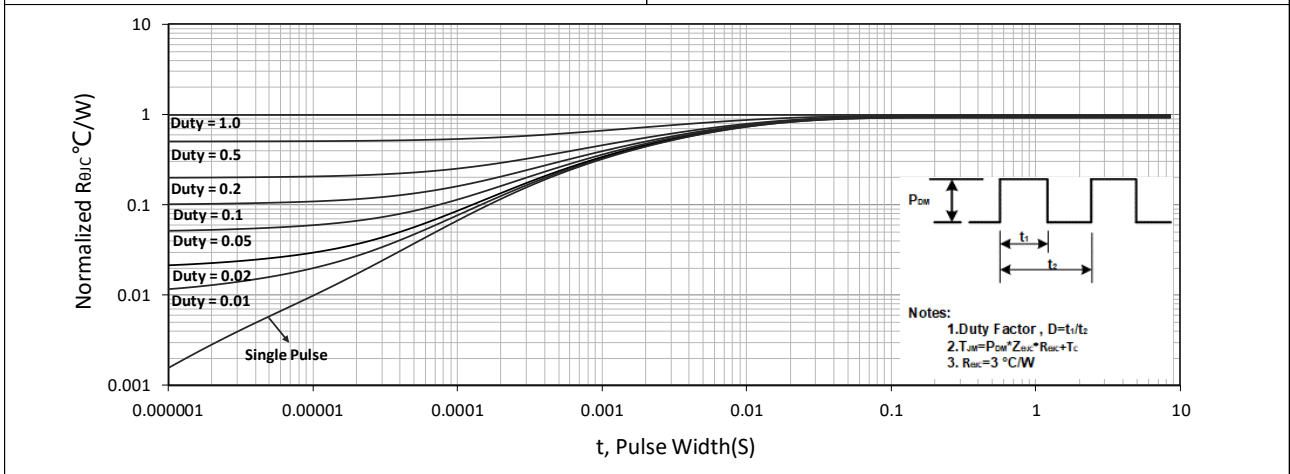


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

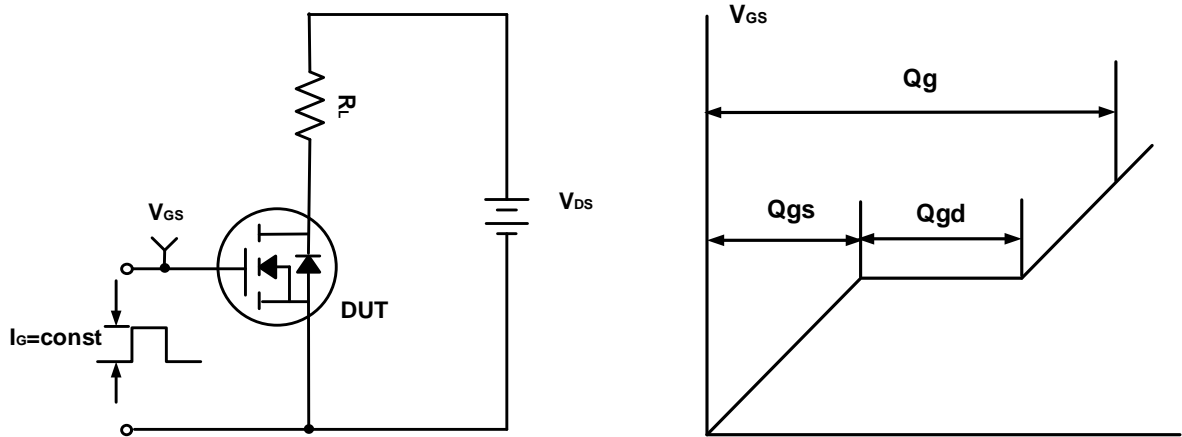


Figure A. Gate Charge Test Circuit & Waveforms

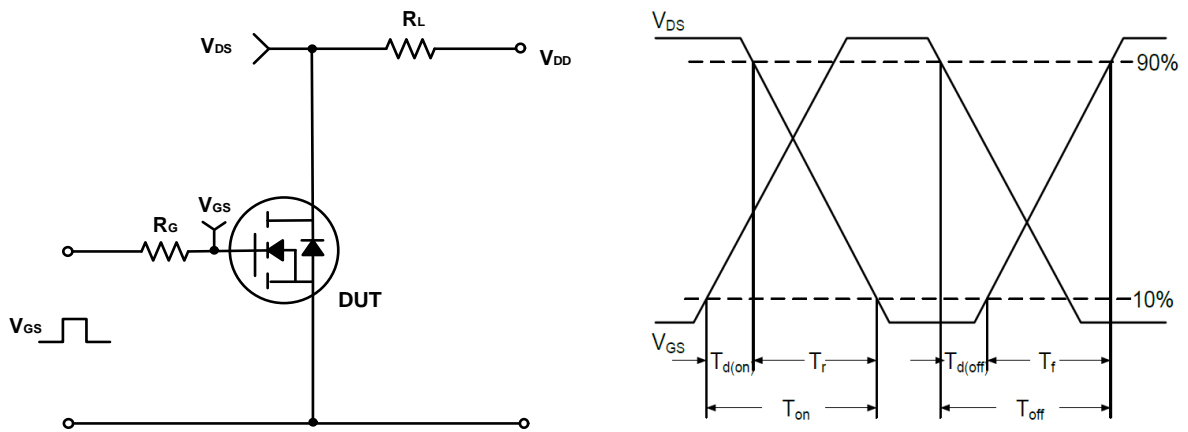


Figure B. Switching Test Circuit & Waveforms

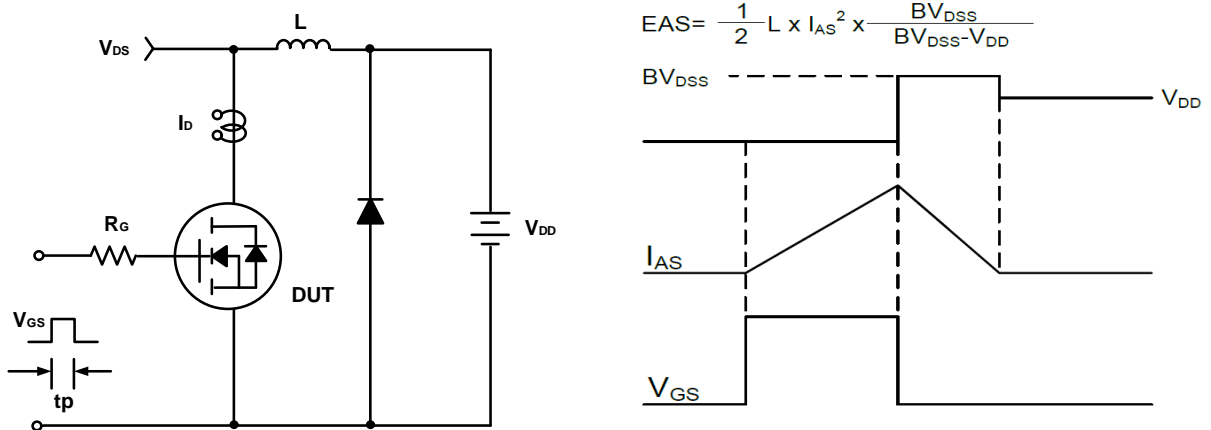
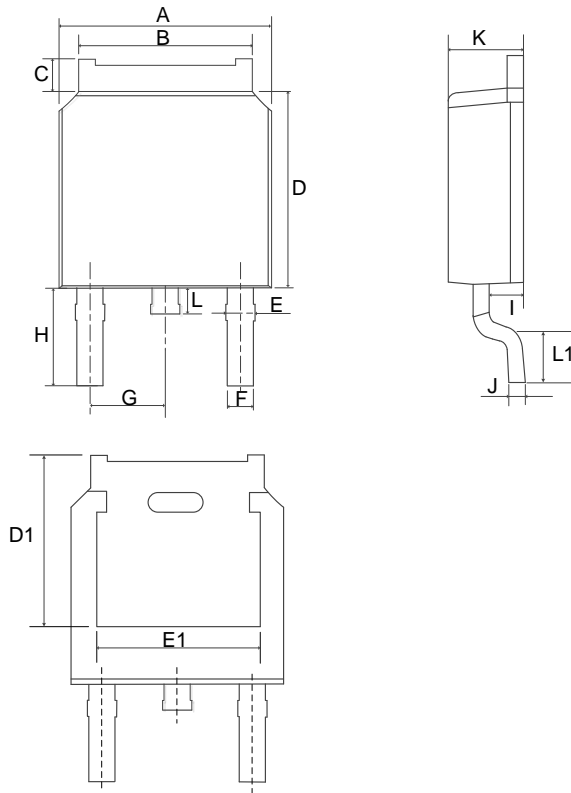


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Mechanical Dimensions for TO-252



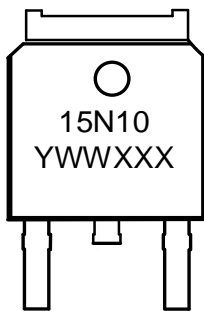
COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	6.40	6.80
B	5.13	5.50
C	0.88	1.28
D	5.90	6.22
D1	5.35REF	
E	0.68	1.10
E1	4.83REF	
F	0.68	0.91
G	2.29REF	
H	2.90REF	
I	0.85	1.17
J	0.51REF	
K	2.10	2.50
L	0.40	1.00
L1	1.50REF	

Ordering Information

Part	Package	Marking	Packing method
15N10	TO-252	15N10	Tape and Reel

Marking Information



15N10 = Device code
YWWXXX= Date code

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